

Date: March 11, 2002

In re Application of: Shinji TAKEDA et al.

Serial No. 09/543,247

Filed: April 5, 2000

For: SEMICONDUCTOR DEVICE AND PROCESS FOR FABRICATION THEREOF

Box: **FEE AMENDMENT**
 ASSISTANT COMMISSIONER FOR PATENTS
 Washington, D. C. 20231

Sir:

Transmitted herewith is an Amendment in the above-identified application.

- [] Small entity status of this application under 37 CFR 1.9 and 1.27 has been established by a verified statement previously submitted.
 [] A verified statement to establish small entity status under 37 CFR 1.9 and 1.27 is enclosed.
 [XXX] No additional fee is required.

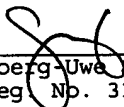
The fee has been calculated as shown below:

(COL. 1)		(COL. 2)		(COL. 3)		SMALL ENTITY		OTHER THAN A SMALL ENTITY	
CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR		PRESENT EXTRA		RATE		ADDIT. OR FEE	
TOTAL	* 14	MINUS	** 35	=	0	X	9 = \$	X	18 = \$ -0-
INDEP.	* 3	MINUS	*** 6	=	0	X	39 = \$	X	78 = \$ -0-
[] FIRST PRESENTATION OF MULTIPLE DEP. CLAIM						X	130 = \$	X	260 = \$ -0-
TOTAL									
ADDIT. FEE \$ _____ OR TOTAL \$ -0-									

- * If the entry in Col. 1 is less than the entry in Col. 2, write "0" in Col. 3.
 ** If the "Highest No. Previously Paid For" IN THIS SPACE is less than 20, write "20" in this space.
 *** If the "Highest No. Previously Paid For" IN THIS SPACE is less than 3, write "3" in this space.
 The "Highest No. Previously Paid For" (Total or Independent) is the highest number found from the equivalent box in Col. 1 of a prior Amendment or the number of claims originally filed.

- [] Please charge my Deposit Account No. 501281 in the amount of \$ _____. A duplicate copy of this sheet is attached.
 [] A check (No. _____) in the amount of \$ _____ is attached.
 [XXX] The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 501281. A duplicate copy of this sheet is attached.

- [XX] Any filing fees under 37 CFR 1.16 for the presentation of extra claims.
 [XX] Any patent application processing fees under 37 CFR 1.17.


 Joerg-Uwe Szapl
 Reg. No. 31,799

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Shinji TAKEDA et al.

Serial No. 09/543,247

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For: SEMICONDUCTOR DEVICE AND
PROCESS FOR FABRICATION
THEREOF

)
) Atty. Docket No.: TM&K0004
)
)
) Group Art Unit: 2814
)
) Examiner: David E. Graybill
)
) Date: March 11, 2002

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AMENDMENT (B)

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the official Office Action dated September 10, 2001 the above captioned application please add the following amendments:

IN THE CLAIMS

Kindly cancel claims 24-34, 36-39, 41, 46-49, and 51 without prejudice.

Please amend claims 17, 19, 20, 23, 35, 40, 42 and 50 as follows:

B1
17. (Amended) A material comprising an organic die-bonding film having a water absorption of 1.5% by volume or less, and the material includes a component that comprises an epoxy resin wherein the epoxy resin is any one of glycidyl ether, glycidylamine, glycidyl ester and an alicyclic epoxy resin.